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1999-529/30

ABSTRACT OF THE DISCLOSURE

0062        Within a method for fabricating a microelectronic fabrication there is first provided a substrate. There is then formed over the substrate a spirally patterned conductor layer which terminates in a microelectronic structure within the center of the spirally patterned conductor layer. The spirally patterned conductor layer forms a planar spiral inductor, and the microelectronic structure formed within the center of the spirally patterned conductor layer further comprises a series of electrically interconnected sub-patterns. The method contemplates a microelectronic fabrication fabricated in accord with the method. The microelectronic fabrication is fabricated with optimal performance while occupying minimal microelectronic substrate area.